

KIOXIA Corporation

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PHONE: 81-45-890-2538
Date: June 12, 2020
Ref. No.: 20MQ-G012(E)

To: _____

Product Change Notification

We are notifying you of planned changes as described below.

1. Affected products

Product type: 32nm 8Gbits 1-stack/2-stack/4-stack SLC NAND TSOP-packaged products

Part number:

TC58NVG3S0FTA00, TC58NVG3S0FTA10, TH58NVG4S0FTA20, TH58NVG4S0FTAK0, TH58NVG5S0FTA20, TH58NVG5S0FTAK0

2. Change description

- An adhesive tape, a material to attach the lead frames in TSOP package will be changed.
- The TSOP package structure will be changed

The changed adhesive materials and the changed package structure have been used in other products.

For details, please see the attached file. The change descriptions differ between the product types.

3. Reason for change

To discontinue the production of the current adhesive tape for end-of life (EOL) in March 2021.

4. Change schedule

Production using the changed materials is scheduled to start in/after October 2020 (running change).

5. Reliability data

Moisture resistance test (MRT), Highly accelerated stress test (HAST) and Temperature cycling (TC) results showed no failures. For test data, please see the attachment file.

6. Evaluation samples

Evaluation samples will be available after early September 2020.

If you request evaluation samples, please inform us by July 10, 2020 as far as possible.

7. Method to identify changed products

You can identify the products before/after the change by additional code printed on labels.

	Additional Code	
Packing	Tray	Tape & Reel
Current	B4H/B4J/B4M	B4Q/B4T
Changed	B4K	B4U

8. Customer response

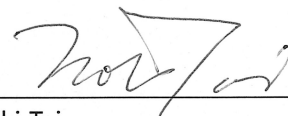
Please notify us of your acceptability of this notification by September 10, 2020.

If we do not receive your any responses within the date above, we will implement this change as scheduled notification.

If you have any inquiry of this subject or a request for evaluation samples, please contact our sales representatives.

We appreciate your understanding and cooperation.

Sincerely,



Nobuyuki Tai
Group Manager
Memory Customer Quality Engineering Group
Memory Q&R Engineering Department
KIOXIA Corporation